| ABSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® INFORMATION AND PARTICIPACITY OF THE STREET OF THE ST | IPC, Bannock   | burn, Illinois. A   | Il rights reserved untions. | under both                          | This docume<br>level parts, t | ent is a declar<br>the declaration                              | ration of<br>n encom | the substance the substance passes all low | es within th<br>ver level m     | e manufactu<br>aterials for w | arer listed it<br>which the m | em. Note<br>anufactu     | e: if the item is an as<br>rer has engineering | ssembly with low responsibility. |  |  |
|---|--|---|-----------------------------|-------------------------------------|-------------------------------|---|----------------------|--|---------------------------------|-------------------------------|-------------------------------|--------------------------|--|----------------------------------|--|--|
|   | IPC Web Site for Information on IPC-1752 Standard Form Typ<br>http://www.ipc.org/IPC-175x Distribute |   |                             |                                     | e *                           | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |                      |  |                                 |                               | rials and Mi                  | ials and Mfg Information |  |                                  |  |  |
| upplier Information   |  |   |                             |                                     |                               |   |                      |  |                                 |                               |                               |                          |  |                                  |  |  |
| Company name*   | Company un   | Company unique ID   |                             |                                     | Unique ID Authority           |   |                      |  |                                 | Respons                       | Response Date*                |                          |  |                                  |  |  |
| onsemi  |  |   |                             |                                     |                               |   |                      |  |                                 |                               | 2023-06-                      | 2023-06-08               |  |                                  |  |  |
| Contact Name  | Title - Conta  | Title - Contact   |                             |                                     | Phone - Contact*              |   |                      |  |                                 | Email -                       | Email - Contact*              |                          |  |                                  |  |  |
| Product-Env-Stewards  | Product Envi   | Product Enviro Compliance                                 |                             |                                     | NA                            |   |                      |  | Product-Env-Stewards@onsemi.com |                               |                               |                          |  |                                  |  |  |
| uthorized Representative*   | Title - Repre  | Title - Representative                                    |                             |                                     | Phone - Representative*       |   |                      |  | Email - Representative*         |                               |                               |                          |  |                                  |  |  |
| Product-Env-Stewards  | Product Enviro Compliance  |   |                             |                                     | NA                            |   |                      |  | Product-Env-Stewards@onsemi.com |                               |                               |                          |  |                                  |  |  |
| Requester Item Number   | Mfr Iter   | Mfr Item Number Mfr Item Name   FSA3357L8X SP3T Analog Sw |                             | Mfr Item Name<br>SP3T Analog Switch |                               | Effective Da  | ate Ve               | e Version N                                |                                 | Manufacturing Site            |                               | Veight*                  | UOM  | Unit Type                        |  |  |
|   | FSA335   |   |                             |                                     |                               | 2023-06-08 TH   |                      | TH2  | TH2                             |                               | .4562                         | mg                       | Each   |                                  |  |  |
| Ianufacturing Proccess Informa  | ation  |   |                             |                                     |                               | 1   |                      |  | 1                               |                               |                               |                          | 1  |                                  |  |  |
| Terminal Plating / Grid Array M   | laterial   | Terminal Base   | Alloy                       | J-STD-020 MSL Rating                |                               | Peak Process Body Temper  |                      | ody Temperat                               | ture Max Time at Peak Ten       |                               | k Temperati                   | are Nur                  | mber of Reflow Cy                              | cles                             |  |  |
| Precious metal (e.g. Ag,Au, NiPdAu) (no<br>Sn)  |  | CU Alloy 1  |                             | 1                                   |                               | 260   |                      | C  | 30                              |                               | second                        | is 3                     |  |                                  |  |  |
| comments  |  |   |                             |                                     |                               |   |                      |  |                                 |                               |                               |                          |  |                                  |  |  |
| vel 1 - maximum time at peak temperat   | ure during so  | oldering is 10-3  | 0 seconds                   |                                     |                               |   |                      |  |                                 |                               |                               |                          |  |                                  |  |  |
| or more information regarding materia   | l composition  | please refer to   | page 3                      |                                     |                               |   |                      |  |                                 |                               |                               |                          |  |                                  |  |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                                 | CAS              | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|---|------------------|--------|--------|-----------------|
| Die                  | 0.1476 | mg              | Supplier | Silicon (Si)                              | 7440-21-3        |        | 0.1476 | mg              |
| Die Attach Epoxy     | 0.0154 | mg              |          | Epoxy resin                               | proprietary data |        | 0.0046 | mg              |
|                      |        |                 | Supplier | Diethylene glycol monoethyl ether acetate | 112-15-2         |        | 0.0054 | mg              |
|                      |        |                 | Supplier | Aluminum Trioxide (Al2O3)                 | 1344-28-1        |        | 0.0054 | mg              |
| Lead Frame           | 1.0344 | mg              | Supplier | Magnesium (Mg)                            | 7439-95-4        |        | 0.0018 | mg              |
|                      |        |                 | Supplier | Silicon (Si)                              | 7440-21-3        |        | 0.0077 | mg              |
|                      |        |                 | В        | Nickel (Ni)                               | 7440-02-0        |        | 0.0336 | mg              |
|                      |        |                 | Supplier | Copper (Cu)                               | 7440-50-8        |        | 0.9914 | mg              |
| Mold Compound-Black  | 2.225  | mg              | Supplier | Carbon Black (C)                          | 1333-86-4        |        | 0.0111 | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)                       | 60676-86-0       |        | 1.958  | mg              |
|                      |        |                 | Supplier | Ortho-Cresol Novolac Resin                | 29690-82-2       |        | 0.1446 | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)                  | 9003-35-4        |        | 0.1112 | mg              |
| Plating              | 0.0146 | mg              | Supplier | Palladium (Pd)                            | 7440-05-3        |        | 0.0011 | mg              |
|                      |        |                 | В        | Nickel (Ni)                               | 7440-02-0        |        | 0.0133 | mg              |
|                      |        |                 | Supplier | Gold (Au)                                 | 7440-57-5        |        | 0.0002 | mg              |
| Wire Bond            | 0.0192 | mg              | Supplier | Palladium (Pd)                            | 7440-05-3        |        | 0.0002 | mg              |
|                      |        |                 | Supplier | Gold (Au)                                 | 7440-57-5        |        | 0.019  | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).